

Timing (TBC)	Name of the session	Scope of expected contributions/pitches	Our EU lead experts
Between 10am and 4pm (timing TBC)	Increasing life of parts – Promote and Uptake innovations	Pitch/present your innovative 3DP/AM-related solutions in the fields of: <ul style="list-style-type: none"> • Repairing and/or • Maintenance. 	Repairing: Paolo Gregori (Trentino Sviluppo/Prom), Damjan Klobcar (University of Ljubljana) Maintenance : Coen de Graaf (Brainport) and Ales Hancic (Tecos)
	Improving Finishing – Promote and Uptake innovations	Pitch/present your innovative solutions in the field of ‘finishing/post-processing of printed parts’, especially when applied to materials different from ‘metal’!	Automated removal and surface smoothing of metal: Helmut Loibl (FOTEC)
	Lighter components - Promote and Uptake innovations	Pitch/present your 3DP-related innovative solutions in terms of developing lighter components.	Hybrid Components: Luca Tomesani (UNIBO)
	More sustainable production – Promote and Uptake innovations	Pitch/present your innovative solutions in terms of using 3DP (and digital technologies) towards improving sustainability of production (material savings, recyclability, etc.).	Smart AM for sustainable production: Maria Colosimo (Polimi) and Marco Luigi Grasso (Polimi)
	The sectors perspective –	Pitch/present your innovative solutions in the field of applying 3DP-related solutions in specific sectors/application areas, in order to address specific sectoral needs. Main focus currently is on ‘Construction’, ‘Healthcare’, and ‘Energy’.	Construction: Theo Salet (TUE) Healthcare: Nicolas Baldini , TBC (IOR) , Xavier Tuto , TBC (Leitat) Energy: Guido Heunen , TBC (Sirris) and Otto von Guericke University, TBC (OVGu, battery modules))
	The parts characteristics perspective	Pitch/present your innovative 3DP/AM-related solutions in the fields of: <ul style="list-style-type: none"> • Printing Large Parts (using technologies other than WAAM preferably) and/or; • Printing parts with Integrated Electronics and/or; • Printing parts in Ceramics. 	Integrated electronics: Hannes Fachberger (FED) Large parts: José Antonio Dieste (Aitiip) and Giulia Marchisio (CIM40) Ceramics: Francesca Mazzanti , TBC (ENEA-TEMAF)